

## Polyimide Selector Guide Aqueous Buffer Coat Materials

Key Characteristic	AP2210B	AN3310
Patterning Density	Positive	Negative
Patterning Wavelength	i-line, g-line, broadband	i-line, g-line, broadband
Typical Photospeed	500mJ/cm <sup>2</sup>	200mJ/cm <sup>2</sup>
Develop Solution	Aqueous TMAH	Aqueous TMAH
Pattern profile	45-60°	80-90°
Resolution in a 10µm film		
Stepper	3µm	7µm
Contact tool	5µm	12µm
Cured Film Properties		
Elongation, %	77	45
CTE, ppm	45	53
% Moisture	< 0.5	< 0.5
Tg	325 °C	305°C
Minimum Cure Temperature	300°C	300°C
Cure environment	Inert	Inert

## Polyimide Selector Guide Negative Acting Photosensitive Products

Key Characteristic	Durimide 7000	Durimide 7300	Durimide 7500
<b>Patterning Wavelength</b>	g-line, broadband	i-line, g-line, broadband	i-line, g-line, broadband
<b>Special Applications</b>	High Tg required	Cu or Ag/ High metal reflectivity	
<b>Typical Photospeed</b>	200mJ/cm <sup>2</sup>	350mJ/cm <sup>2</sup>	150mJ/cm <sup>2</sup>
<b>Develop Solution</b>	Solvent	Solvent	Solvent
<b>Pattern profile</b>	80-90°	80-90°	80-90°
<b>Resolution in a 10µm film</b>			
<b>Stepper</b>	6µm	4-5µm	4-5µm
<b>Contact tool</b>	12µm	10µm	10µm
<b>Cured Film Properties</b>			
<b>Elongation, %</b>	73	85	85
<b>CTE, ppm</b>	27	55	55
<b>% Moisture</b>	1.3	1.08	1.08
<b>Tg</b>	> 350 °C	285 °C	285°C
<b>Minimum Cure Temperature</b>	350°C	315°C	315°C
<b>Cure environment</b>	Inert	Inert	Inert

## Polyimide Selector Guide

### Non-Photosensitive Preimidized Products

Key Characteristic	Durimide 10/32A Series	Durimide 200 Series	Durimide 20 Series
<b>Polyimide Structure</b>	Polyamide-imide	Preimidized polyimide	Preimidized polyimide
<b>Typical Applications</b>	Drop, coating, low temp cure	Lift-off, low temp cure	Thin Lift off layers
<b>Patterning</b>	Dry, hard mask required	Dry, hard mask required	Dry, hard mask required
<b>Develop Solution</b>	CF <sub>4</sub> / O <sub>2</sub> Plasma	CF <sub>4</sub> / O <sub>2</sub> Plasma	CF <sub>4</sub> / O <sub>2</sub> Plasma
<b>Pattern profile</b>	80-90°	80-90°	80-90°
<b>Cured Film Properties</b>			
<b>Elongation, %</b>	56	75	75
<b>CTE, ppm</b>	53	54	54
<b>% Moisture</b>	--	1.1	1.1
<b>Tg</b>	300 °C	309 °C	309°C
<b>Minimum Cure Temperature</b>	250°C	250°C	200-250°C
<b>Cure environment</b>	Inert	Inert	Inert

## Polyimide Selector Guide Non-Photosensitive Polyamic Acid Products

Key Characteristic	LTP10-18A	Durimide 100 Series
Polyimide Structure	Polyamic acid	Polyamic acid
Typical Applications	Low temperature cure	Buffer coat, redistribution layers
Patterning	Wet etch transfer from photoresist pattern	Wet etch transfer from photoresist pattern
Develop Solution	Aqueous TMAH	Aqueous TMAH
Pattern profile	45-60°	45-60°
Cured Film Properties		
Elongation, %	75	80
CTE, ppm	46	32
% Moisture		1.7
Tg	265 °C	385°C
Minimum Cure Temperature	250°C	350°C
Cure environment	Inert	Inert

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